

	Heat Sink for Xeon Series					
Item	Part Number	Description	Dimension	Photo	Application	
1W	OSMCPCB8060B	 Aluminum metal-base copper-clad laminate PCB Design for Xeon 1 Power Series LED Base metal is 1.5mm Aluminum With NTCD Thermally Conductive Dielectric Copper Circuit Foil is 35 µ m(1oz) Surface Finish is Black Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	Unit:mm Tolerance:±0.30mm		Used for Xeon 1 Power Series, eg: OSW4XME1C1E	
3W	OSMCPCB8060A	 Aluminum metal-base copper-clad laminate PCB Design for Xeon 3 Power Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 µ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	Unit:mm Tolerance:±0.30mm		Used for Xeon 3 Power Series, eg: OSW4XME3C1E	



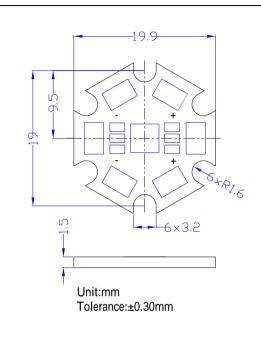
3W	OSMCPCB8086D	 Aluminum metal-base copper-clad laminate PCB Design for 3pcs Xeon 1 Power Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 µ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	**************************************	Used for 3pcs Xeon 1 Power Series, eg:OSW4XME1C1E
RGB	OSMCPCB8060C	 Aluminum metal-base copper-clad laminate PCB Design for Xeon 1 Power RGB Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 µ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	Unit:mm Tolerance:±0.30mm	Used for Xeon 1 Power RGB Series, eg:OSTCXBEAC1E



	Heat Sink for Tops Power Series					
Item	Part Number	Description	Dimension	Photo	Application	
1W	OSMCPCB5050B	 Aluminum metal-base copper-clad laminate PCB Design for Tops 1 Power Series LED Base metal is 1.5mm Aluminum With NTCD Thermally Conductive Dielectric Copper Circuit Foil is 35 µ m(1oz) Surface Finish is Black Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	Unit:mm Tolerance:±0.30mm		Used for Tops 1 Power Series, eg: OSW4XAT1C1E	
3W	OSMCPCB5050C	 Aluminum metal-base copper-clad laminate PCB Design for Tops 3 Power Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 µ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	Unit:mm Tolerance:±0.30mm		Used for Tops 3 Power Series, eg: OSW4XAT3C1E	



	OSMCPCB5050A	•	Aluminum metal-base copper-clad
			laminate PCB
		•	Design for Tops 0.5 Power RGB Series
			LED
		•	Base metal is 1.5mm Aluminum
		•	With HTCD Thermally Conductive
D.C.D.			Dielectric to suitable high power LED
RGB		•	Copper Circuit Foil is 35 µ m(1oz)
		•	Surface Finish is White Solder Mask,
			Pb-free HASL solder pads (RoHS
			compliant)





Used for Tops 0.5

Power RGB Series,
eg:
OSTCXBTHC1E

Heat Sink for Commercial Series

Item	Part Number	Description	Dimension	Photo	Application
RGB	OSMCPCB9218A	 Aluminum metal-base copper-clad laminate PCB Design for Commercial 1 Power RGB Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 µ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	Unit:mm Tolerance:±0.30mm		Used for Commercial 1 Power RGB Series, eg: OSTCXBC1C1E



Appendix

Data and information for MCPCB

Items	Unit	Reference
Thermal Conductivity	W/mK	0.8W/mK
Dielectric thickness	μ m	100
Breakdown voltage	kV(DC)	> 3kV
Insulation resistance		10 ⁵
Maximum Working Temperature		130
Peel Strength	N/mm	> 1.4
Blistering after heat shock within 1 minutes		<260
Copper thickness	μ m	35
Base metal plate	-	Aluminum
Base metal thickness	mm	1.5